MODEL: HSB34-282811 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy
- black anodized finish

RoHS

MODEL

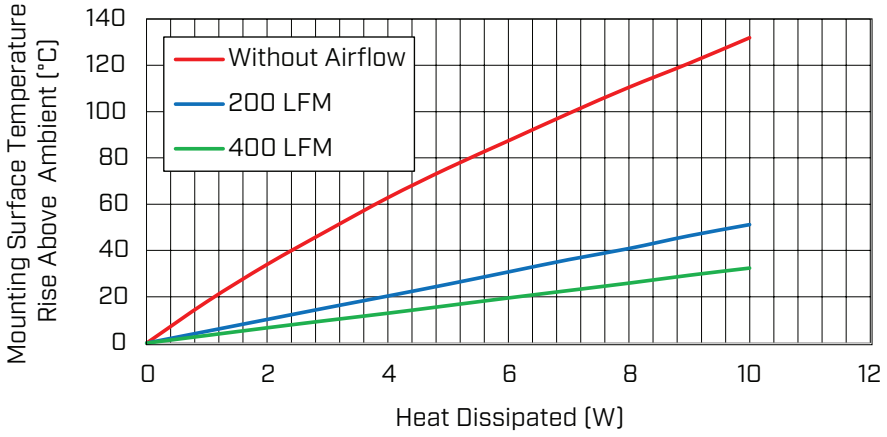
	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSB34-282811	15.05	17.9	5.1	3.3	4.98

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	17.9	5.1	3.3
2	34.0	10.2	6.6
3	48.6	15.3	9.8
4	62.8	20.3	12.9
5	75.6	25.4	16.2
6	87.4	30.7	19.5
7	99.2	36.0	22.7
8	110.5	40.8	25.9
9	120.9	46.3	29.3
10	131.9	51.1	32.4

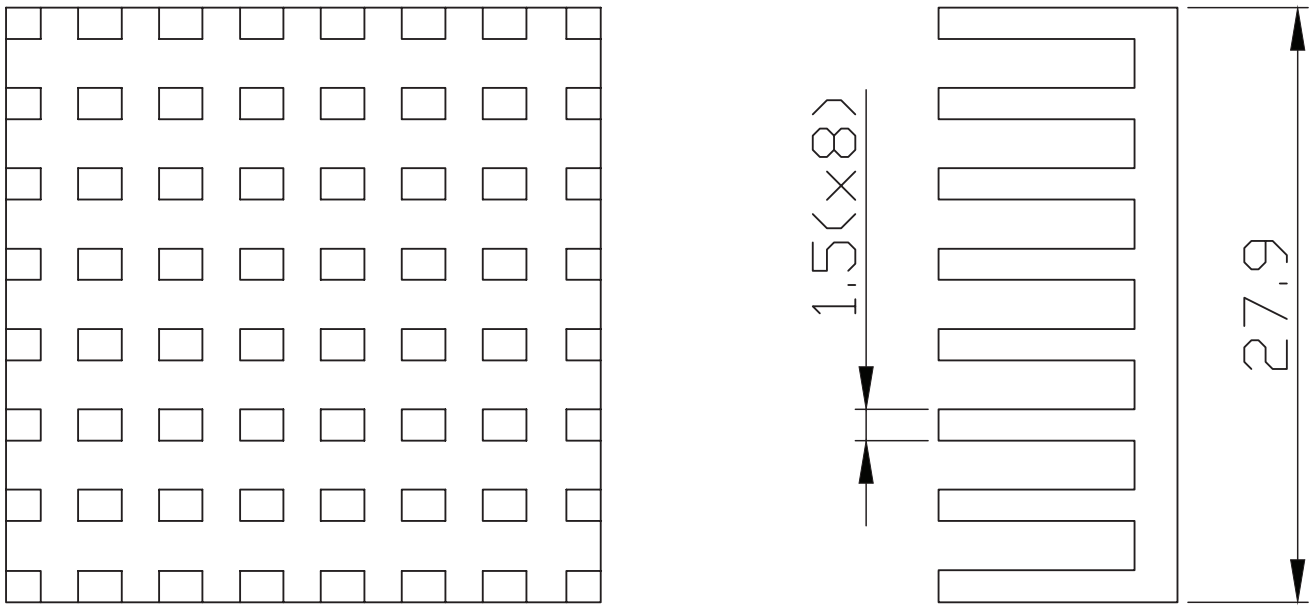
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature

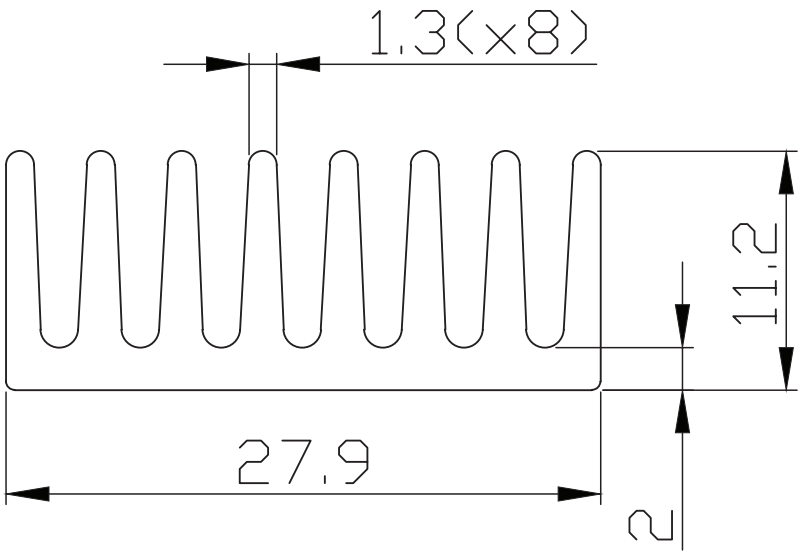


MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	9 g





REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024
1.01	CUI Devices rebranded to Same Sky	09/12/2024

The revision history provided is for informational purposes only and is believed to be accurate.